

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 – 3 (Cancelled)

4. (Currently Amended) A print assembly for pagewidth inkjet printing, the print assembly comprising

an elongate carrier that is mountable on a support structure of a printer in an operative position with respect to a platen of the printer;

a number of printhead chips positioned on the carrier, the printhead chips each having a plurality of ink ejection nozzle arrangements on a wafer substrate, each nozzle arrangement having an actuator for ejecting ink from an associated nozzle when a resistive element of said actuator is heated by an electrical current supplied by drive circuitry on the wafer substrate; and

at least one a plurality of controllers, each controller mounted on a respective printed circuit board that is positioned on the carrier, the each controller being connected to a plurality of the printhead chips via a individual flexible printed circuit board-boards of each printhead chip and to the other controllers, and each controller being configured to control operation of at least 10,000 nozzle arrangements of the connected printhead chips.

5. - 6. (Cancelled)

7. (Previously Presented) A print assembly as claimed in claim 4, in which the printhead chips together incorporate at least one hundred thousand nozzle arrangements.

8. (Previously Presented) A print assembly as claimed in claim 4, in which the printhead chips together incorporate at least two hundred thousand nozzle arrangements.

9. (Original) A print assembly as claimed in claim 8, which includes between forty and one hundred printhead chips positioned on the carrier.

10. (Original) A print assembly as claimed in claim 4, in which each printhead chip is the product of an integrated circuit fabrication process.

11. (Previously Presented) A print assembly as claimed in claim 10, in which and the drive circuitry is comprised in a CMOS drive circuitry layer positioned on the wafer substrate with the nozzle arrangements positioned on the wafer substrate and the CMOS drive circuitry layer.

12. (Previously Presented) A print assembly as claimed in claim 11, in which each nozzle arrangement is electrically connected to the CMOS drive circuitry layer.

13. (Original) A print assembly as claimed in claim 12, which includes a plurality of printhead modules, each printhead module incorporating a printhead chip, the printhead modules being mounted on the carrier.

14-20. (Cancelled)